



MATERIAL DATA FORM

Manufacturer contact Information

Contact Name	Compliance Coordinator
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Manufacturer's Part Number.	Total Mass of the Unit specified in (g):	Material Name	Substance Name	IMDS No.	Substance Mass (mg)	% Weight of Assembly	PPM of Total Assembly
MBR30xxCTP	1.33	Die,Schottky	Doped silicon	TBD	8.7278	0.65%	6539
Customer's Partnumber.		ITO220S leadframe	KFC(PMC 90)	TBD	365.6400	27.39%	273949
			Die attached pad plating	TBD	0.5758	0.04%	431
		Heatsink	6063 Alloy	TBD	432.0540	32.37%	323709
		Bonding wire	Aluminum	TBD	7.9994	0.60%	5993
		Molding compound	CEL-3650	TBD	505.5890	37.88%	378804
		High temperature solder	PbSnAg Alloy	TBD	7.1609	0.54%	5365
		Tin solder	Pure Tin	37508652	6.9516	0.52%	5208

Total (mg)	1334.699
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MATERIAL DATA FORM DETAIL

Manufacturer's Part Number.	Total Mass of the Unit specified in (g):	Material Name	Generic ID	Element	CAS No.	Substance Mass (mg)	% of Weight (Sub Assembly Material)	PPM of Sub Assembly Material	PPM of Total Weight
MBR30xxCTP	1.335	Die,Schottky	Doped silicon	Si	7440-21-3	8.7278	100.00%	1000000	6539
Customer's Partnumber.		ITO220S leadframe	KFC(PMC90)	Fe	1309-37-1	0.3656	0.10%	1000	274
				P	7723-14-0	0.1097	0.03%	300	82
				Cu	7440-50-8	365.1647	99.87%	998700	273593
			Pure Nickel	Ni	7440-02-0	0.5758	100.00%	1000000	431
		Heatsink	6063 Alloy	Si	7440-21-3	1.7282	0.40%	4000	1295
				Fe	1309-37-1	1.5122	0.35%	3500	1133
				Cu	7440-50-8	0.4321	0.10%	1000	324
				Mn	7439-96-5	0.4321	0.10%	1000	324
				Mg	7439-95-4	3.0244	0.70%	7000	2266
				Cr (Not CrVI)	7440-47-3	0.4321	0.10%	1000	324
				Zn	7440-66-6	0.4321	0.10%	1000	324
				Ti	7440-32-6	0.4321	0.10%	1000	324
		Bonding wire	15 mil	Al	7429-90-5	423.6289	98.05%	980500	317397
		Molding compound	CEL-3650	Epoxy Resin	-----	55.6148	11.00%	110000	41668
				Phenol Resin	-----	25.2795	5.00%	50000	18940
				Carbon black	1309-64-4	1.0112	0.20%	2000	758
				Sb2O3	1309-64-4	5.0559	1.00%	10000	3788
				Brominated Epox	40039-93-8	15.1677	3.00%	30000	11364
				Silica	14808-60-7	403.4600	79.80%	798000	302285
		High temperature solder	Pb5Sn2.5Ag	Pb	7439-92-1	6.6239	92.50%	925000	4963
				Ag	7440-22-4	0.1790	2.50%	25000	134
				Sn	7440-31-5	0.3580	5.00%	50000	268
		Tin solder	Pure Tin	Sn	7440-31-5	6.9516	100.00%	1000000	5208

Total (mg) 1334.699

MATERIALS DISCLOSURE DISCLAIMER

1. The materials are disclosed according to JIG-101 "Material Composition Declaration for Electronic Products"

2. Even though all possible efforts have been made to provide you with the most accurate information, we can not guarantee its completeness and accuracy due to the fact that the data has been compiled based on information provided by our subcontractors and raw material suppliers. Complete information may not have been provided to protect their business proprietary information. Based on the above considerations, this information is provided only as estimates of the average weight of these parts and the anticipated significant toxic metals components.

3. These estimates do not include trace levels of dopants and metal materials within the silicon devices contained inside of the finished products.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELVII and RoHS and reported above:

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|--------------------------------------------------------------|----------------------------------------------------------------------------------------|
| 1. Asbestos | 11. Ozone Depleting Substances - Class II (HCFCs) |
| 2. Azo compounds | 12. Perfluorooctane Sulphonate (PFOS) or related compounds |
| 3. Cadmium and cadmium compounds | 13. Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including |
| 4. Certain Shortchain Chlorinated Paraffins | DecaBDE |
| 5. Chlorinated organic compounds | 14. Polychlorinated Biphenyls (PCBs) |
| 6. Hexavalent chromium compounds | 15. Polychlorinated Naphthalenes (>3 chlorine atoms) |
| 7. Lead and lead compounds | 16. Radioactive Substances |
| 8. Mercury and mercury compounds | 17. Tributyl Tin (TBT) and Triphenyl Tin (TPT) |
| 9. Organic tin compounds | 18. Tributyl Tin Oxide (TBTO) |
| 10. Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.) | |

This product or product family meet REACH requirements for chemicals designated by the European Chemicals Agency (ECHA) as Substances of Very High Concern (SVHC) appended below:

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|---------------------------------|-------------------------------------------------------------------------|
| 1. Anthracene | 9. Bis (2-ethyl(hexyl)phthalate) (DEHP) |
| 2. 4,4'- Diaminodiphenylmethane | 10. Hexabromocyclododecane (HBCDD) |
| 3. Dibutyl phthalate (DBP) | 11. Bis(tributyltin)oxide (TBTO) |
| 4. Cyclododecane | 12. Lead hydrogen arsenate |
| 5. Cobalt dichloride | 13. Triethyl arsenate |
| 6. Diarsenic pentaoxide | 14. Benzyl butyl phthalate (BBP) |
| 7. Diarsenic trioxide | 15. 5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene) |
| 8. Sodium dichromate, dihydrate | 16. Alkanes, C10-13, chloro (SCCPs - Short Chain Chlorinated Paraffins) |